
AMENDMENTS TO THE SPECIFICATION

Please replace the title with the following substitute title:

SYNCHRONOUS NON-VOLATILE MEMORY SYSTEM

Please replace the paragraph starting on page 6, line 28 with the following amended paragraph:

Q2
Figure 1B illustrates an interconnect pin assignment of one embodiment of the present invention. The memory package 150 has 54 interconnect pins. The pin configuration is substantially similar to available SDRAM packages. Two interconnects specific to the present invention are RP# 152 and Vccp 154. Although the present invention may share interconnect labels that ~~are appear~~ appear the same as SDRAM's, the function of the signals provided on the interconnects are described herein and should not be equated to SDRAM's unless set forth herein. Figure 1C illustrates one embodiment of a memory package 160 that has solder bump connections instead of the pin connections of Figure 1C. The present invention, therefore, is not limited to a specific package configuration.
